



PCB THICKNESS	DIM P	MATERIAL NUMBER
.125 3.18	.177 4.50	45515-0001
.093 2.36	.143 3.60	45515-0002
.062 1.57	.115 2.92	45515-0003

- NOTES:
- HOUSING MATERIAL: LCP, 30% GLASS FILLED, UL94V-0, BLACK
TERMINAL MATERIAL: COPPER ALLOY - C7026 (TMOS)
BLADE MATERIAL: COPPER ALLOY - C110
 - FINISH: SELECT GOLD: 30 MI MIN
SELECT TIN: 150 / 250 MI
BOTH OVER NICKEL: 50 MI MIN
 - PRODUCT SPECIFICATION: PS-45424-001
 - PACKAGING SPECIFICATION: ES-45483-999
 - PRODUCT AND/OR PROCESS CHANGES MUST BE APPROVED BY MOLEX ENGINEERING PRIOR TO IMPLEMENTATION.
 - DIMENSIONS GIVEN ACROSS CENTERLINES ARE SYMMETRICAL ABOUT THOSE CENTERLINES WITHIN HALF THE TOTAL TOLERANCE.
 - TERMINAL RETENTION IN HOUSING: 2.5 LBS MIN.
 - THIS MODULE MUST INTERLOCK WITH ALL STANDARD MOLEX POWER DOCK MODULES.
 - PART IS RoHS COMPLIANT. SEE ES-45483-999 FOR LABEL REQUIREMENTS.

PCB LAYOUT: COMPONENT SIDE
PCB TOLERANCE: ± 0.05

STANDARDIZATION	DESCRIPTION
EC NO: UCP2005-1675	
DRWN:KSAMIEC 2005/11/29	
CHKD:KSAMIEC 2005/11/29	
APPR:APATEL 2005/12/12	
B	REV

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES \pm ---	\pm ---
3 PLACES \pm ---	\pm ---
2 PLACES ± 0.15	\pm ---
1 PLACE ± 0.25	\pm ---
ANGULAR $\pm 1/2^\circ$	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
SCHAFFER	2005/2/17
CHECKED BY	DATE
SAMIEC	2005/2/8
APPROVED BY	DATE
MARGULIS	2005/2/9
MATERIAL NO. SEE CHART	
SIZE	A

SCALE 1.5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE POWER DOCK MODULE SIGNAL SOCKET 24 PIN VERTICAL SOLDER TAIL		
MOLEX INCORPORATED		
MATERIAL NO. SD-45515-001	SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		